

CGH40006P

6 W, RF Power GaN HEMT

Cree's CGH40006P is an unmatched, gallium nitride (GaN) high electron mobility transistor (HEMT). The CGH40006P, operating from a 28 volt rail, offers a general purpose, broadband solution to a variety of RF and microwave applications. GaN HEMTs offer high efficiency, high gain and wide bandwidth capabilities making the CGH40006P ideal for linear and compressed amplifier circuits. The transistor is available in a solder-down, pill package.



Package Types: 440109 PN's: CGH40006P

FEATURES

- Up to 6 GHz Operation
- 13 dB Small Signal Gain at 2.0 GHz
- 11 dB Small Signal Gain at 6.0 GHz
- 8 W typical at P_{IN} = 32 dBm
- 65 % Efficiency at P_{IN} = 32 dBm
- 28 V Operation

APPLICATIONS

- 2-Way Private Radio
- Broadband Amplifiers
- Cellular Infrastructure
- Test Instrumentation
- Class A, AB, Linear amplifiers suitable for OFDM, W-CDMA, EDGE, CDMA waveforms







Absolute Maximum Ratings (not simultaneous) at 25°C Case Temperature

| Parameter | Symbol | Rating | Units | Conditions |
|---|--------------------------|-----------|-------|------------|
| Drain-Source Voltage | V _{DSS} | 84 | Volts | 25°C |
| Gate-to-Source Voltage | V _{GS} | -10, +2 | Volts | 25°C |
| Storage Temperature | T _{STG} | -65, +150 | °C | |
| Operating Junction Temperature | T _J | 225 | °C | |
| Maximum Forward Gate Current | I _{GMAX} | 2.1 | mA | 25°C |
| Maximum Drain Current ¹ | I _{DMAX} | 0.75 | Α | 25°C |
| Soldering Temperature ² | T _s | 245 | °C | |
| Thermal Resistance, Junction to Case ³ | $R_{_{	ext{	ilde HJC}}}$ | 9.5 | °C/W | 85°C |
| Case Operating Temperature ³ | T _c | -40, +150 | °C | |

Note

Electrical Characteristics (T_c = 25°C)

| Characteristics | Symbol | Min. | Тур. | Max. | Units | Conditions | | |
|---|---------------------|------------|------|------|-----------------|--|--|--|
| DC Characteristics ¹ | | | | | | | | |
| Gate Threshold Voltage | $V_{\text{GS(th)}}$ | -3.8 | -3.0 | -2.3 | V _{DC} | $V_{DS} = 10 \text{ V, I}_{D} = 2.1 \text{ mA}$ | | |
| Gate Quiescent Voltage | $V_{\rm GS(Q)}$ | - | -2.7 | - | V _{DC} | $V_{DS} = 28 \text{ V, I}_{D} = 100 \text{ mA}$ | | |
| Saturated Drain Current | I _{DS} | 1.7 | 2.1 | - | А | $V_{DS} = 6.0 \text{ V}, V_{GS} = 2.0 \text{ V}$ | | |
| Drain-Source Breakdown Voltage | $V_{\rm BR}$ | 120 | - | - | V _{DC} | $V_{GS} = -8 \text{ V, } I_{D} = 2.1 \text{ mA}$ | | |
| RF Characteristics ² (T _c = 25°C, F ₀ = 2.0 GH | z unless otherwi | ise noted) | | | | | | |
| Small Signal Gain | $G_{\mathtt{SS}}$ | 11.5 | 13 | - | dB | $V_{DD} = 28 \text{ V, } I_{DQ} = 100 \text{ mA}$ | | |
| Power Output at P _{IN} = 32 dBm | P _{out} | 7.0 | 9 | - | W | V _{DD} = 28 V, I _{DQ} = 100 mA | | |
| Drain Efficiency ³ | η | 53 | 65 | - | % | $V_{DD} = 28 \text{ V, } I_{DQ} = 100 \text{ mA, } P_{IN} = 32 \text{ dBm}$ | | |
| Output Mismatch Stress | VSWR | - | - | 10:1 | Ψ | No damage at all phase angles, V_{DD} = 28 V, I_{DQ} = 100 mA, P_{IN} = 32 dBm | | |
| Dynamic Characteristics | | | | | | | | |
| Input Capacitance | C _{GS} | - | 3.0 | _ | pF | $V_{DS} = 28 \text{ V, } V_{gs} = -8 \text{ V, } f = 1 \text{ MHz}$ | | |
| Output Capacitance | C _{DS} | - | 1.1 | - | pF | $V_{DS} = 28 \text{ V, } V_{gs} = -8 \text{ V, } f = 1 \text{ MHz}$ | | |
| Feedback Capacitance | C _{GD} | - | 0.1 | - | pF | $V_{DS} = 28 \text{ V, } V_{gs} = -8 \text{ V, } f = 1 \text{ MHz}$ | | |

Notes.

¹ Current limit for long term, reliable operation

² Refer to the Application Note on soldering at <u>www.cree.com/RF/Document-Library</u>

 $^{^{\}rm 3}$ Measured for the CGH40006P at P $_{\rm DISS}$ = 8 W.

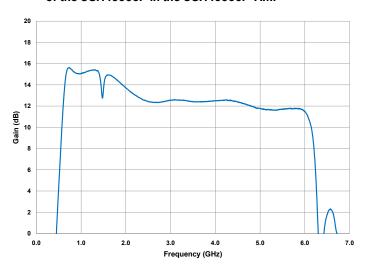
¹ Measured on wafer prior to packaging.

² Measured in CGH40006P-AMP.

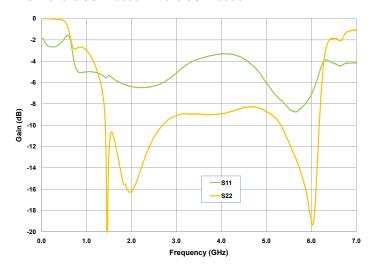
 $^{^{3}}$ Drain Efficiency = P_{out} / P_{DC}



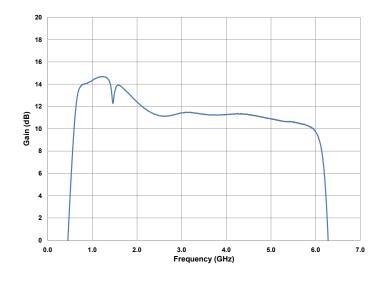
Small Signal Gain vs Frequency at 28 V of the CGH40006P in the CGH40006P-AMP



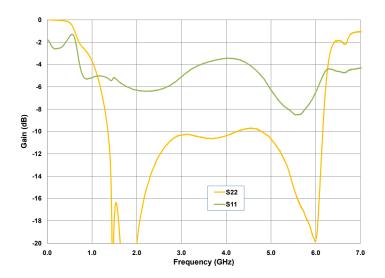
Input & Output Return Losses vs Frequency 28 V of the CGH40006P in the CGH40006P-AMP



Small Signal Gain vs Frequency at 20 V CGH40006P in the CGH40006P-AMP

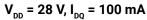


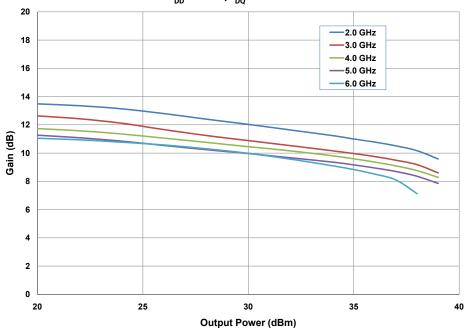
Input & Output Return Losses vs Frequency at of the 20 V of the CGH40006P in the CGH40006P-AMP



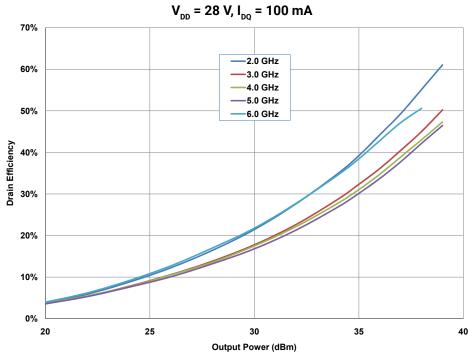


Power Gain vs Output Power as a Function of Frequency of the CGH40006P in the CGH40006P-AMP



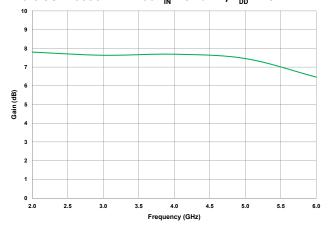


Drain Efficiency vs Output Power as a Function of Frequency of the CGH40006P in the CGH40006P-AMP

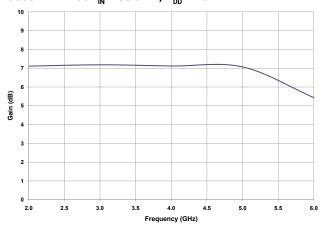




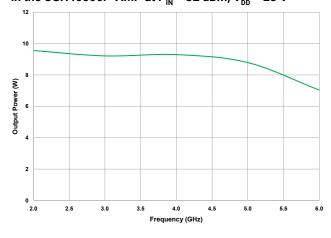
Power Gain vs Frequency of the CGH40006P in the CGH40006P-AMP at P_{IN} = 32 dBm, V_{DD} = 28 V



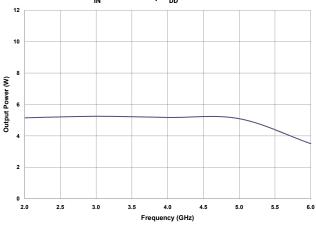
Power Gain vs Frequency of the CGH40006P in the CGH40006P-AMP at P_{IN} = 30 dBm, V_{DD} = 20 V



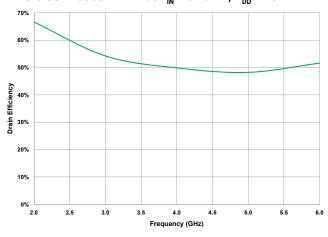
Output Power vs Frequency of the CGH40006P in the CGH40006P-AMP at P_{IN} = 32 dBm, V_{DD} = 28 V



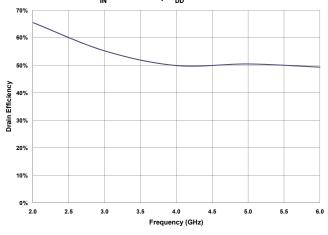
Output Power vs Frequency of the CGH40006P in the CGH40006P-AMP at P_{IN} = 30 dBm, V_{DD} = 20 V



Drain Efficiency vs Frequency of the CGH40006P in the CGH40006P-AMP at P_{IN} = 32 dBm, V_{DD} = 28 V

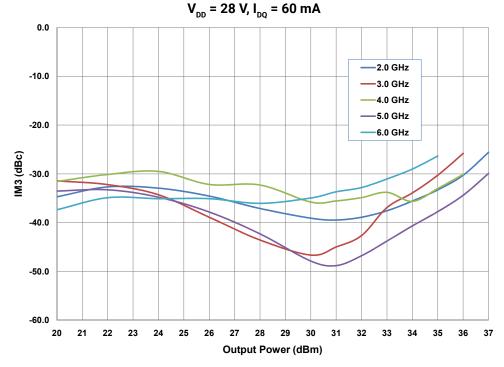


Drain Efficiency vs Frequency of the CGH40006P in the CGH40006P-AMP at $P_{IN} = 30$ dBm, $V_{DD} = 20$ V

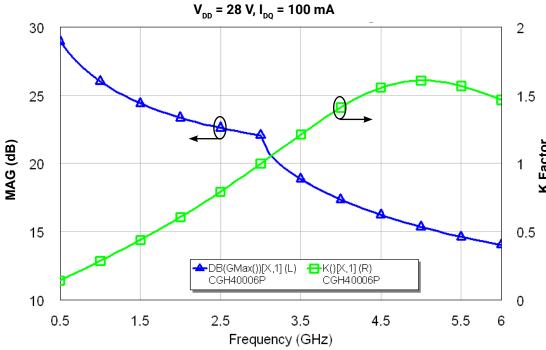




Third Order Intermodulation Distortion vs Average Output Power as a Function of Frequency of the CGH40006P in the CGH40006P-AMP



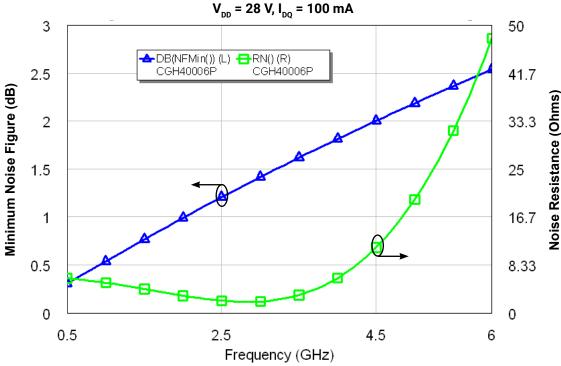
Simulated Maximum Available Gain and K Factor of the CGH40006P





Typical Noise Performance



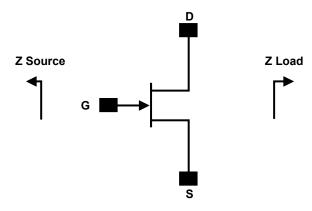


Electrostatic Discharge (ESD) Classifications

| Parameter | Symbol | Class | Test Methodology |
|---------------------|--------|------------|---------------------|
| Human Body Model | НВМ | 1A > 250 V | JEDEC JESD22 A114-D |
| Charge Device Model | CDM | 1 < 200 V | JEDEC JESD22 C101-C |



Source and Load Impedances



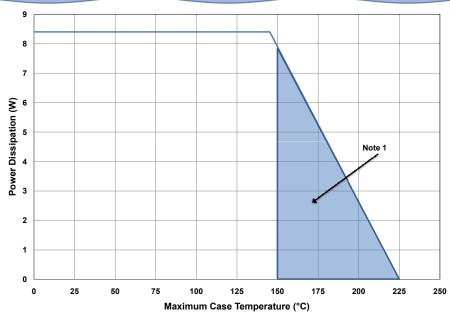
| Frequency (MHz) | Z Source | Z Load |
|-----------------|---------------|---------------|
| 1000 | 13.78 + j6.9 | 61.5 + j47.4 |
| 2000 | 4.78 + j1.78 | 19.4 + j39.9 |
| 3000 | 2.57 - j6.94 | 12.57 + j23.1 |
| 4000 | 3.54 - j14.86 | 9.44 + j11.68 |
| 5000 | 4.42 - j25.8 | 9.78 + j4.85 |
| 6000 | 7.1 - j42.7 | 9.96 - j4.38 |

Note 1. V_{DD} = 28V, I_{DQ} = 100mA in the 440109 package.

Note 2. Optimized for power gain, \mathbf{P}_{SAT} and PAE.

Note 3. When using this device at low frequency, series resistors should be used to maintain amplifier stability.

CGH40006P Power Dissipation De-rating Curve



Note 1. Area exceeds Maximum Case Operating Temperature (See Page 2).



CGH40006P-AMP Demonstration Amplifier Circuit Bill of Materials

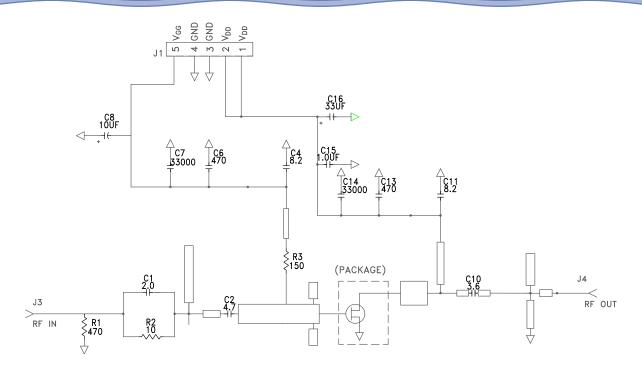
| Designator | Description | Qty |
|------------|--|-----|
| R1 | RES, AIN, 0505, 470 Ohms (≤5% tolerance) | 1 |
| R2 | RES, AIN, 0505, 10 Ohms (≤5% tolerance) | 1 |
| R3 | RES, AIN, 0505, 150 Ohms (≤5% tolerance) | 1 |
| C1 | CAP, 2.0 pF +/-0.1 pF, 0603, ATC 600S | 1 |
| C2 | CAP, 4.7 pF +/-0.1 pF, 0603, ATC 600S | 1 |
| C10 | CAP, 3.6 pF +/-0.1 pF, 0603, ATC 600S | 1 |
| C4,C11 | CAP, 8.2 pF +/-0.25, 0603, ATC 600S | 2 |
| C6,C13 | CAP, 470 pF +/-5%, 0603, 100 V | 2 |
| C7,C14 | CAP, 33000 pF, CER, 100V, X7R, 0805 | 2 |
| C8 | CAP, 10 uf, 16V, SMT, TANTALUM | 1 |
| C15 | CAP, 1.0 uF +/-10%, CER, 100V, X7R, 1210 | 1 |
| C16 | CAP, 33 uF, 100V, ELECT, FK, SMD | 1 |
| J3,J4 | CONN, SMA, STR, PANEL, JACK, RECP | 2 |
| J1 | HEADER RT>PLZ .1CEN LK 5POS | 1 |
| - | PCB, RO5880, 20 MIL | 1 |
| Q1 | CGH40006P | 1 |

CGH40006P-AMP Demonstration Amplifier Circuit

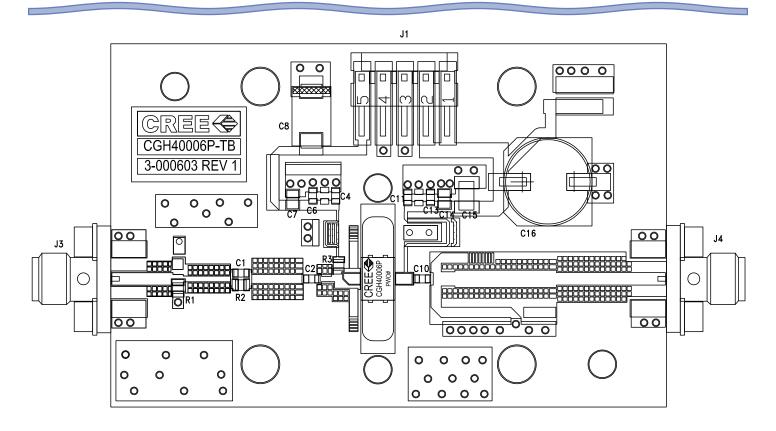




CGH40006P-AMP Demonstration Amplifier Circuit Schematic



CGH40006P-AMP Demonstration Amplifier Circuit Outline





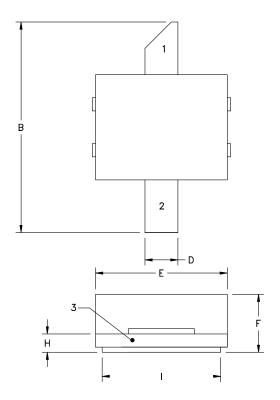
Typical Package S-Parameters for CGH40006P (Small Signal, $V_{\rm DS}$ = 28 V, $I_{\rm DQ}$ = 100 mA, angle in degrees)

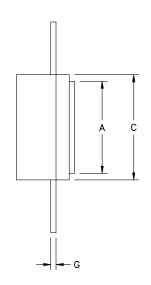
| Frequency | Mag S11 | Ang S11 | Mag S21 | Ang S21 | Mag S12 | Ang S12 | Mag S22 | Ang S22 |
|-----------|---------|---------|---------|---------|---------|---------|---------|---------|
| 500 MHz | 0.905 | -96.56 | 18.30 | 120.62 | 0.023 | 35.87 | 0.456 | -52.76 |
| 600 MHz | 0.889 | -107.98 | 16.39 | 113.31 | 0.025 | 29.63 | 0.429 | -58.98 |
| 700 MHz | 0.877 | -117.55 | 14.76 | 106.99 | 0.026 | 24.39 | 0.408 | -64.31 |
| 800 MHz | 0.867 | -125.66 | 13.37 | 101.43 | 0.027 | 19.92 | 0.393 | -68.96 |
| 900 MHz | 0.860 | -132.61 | 12.19 | 96.46 | 0.028 | 16.05 | 0.381 | -73.11 |
| 1.0 GHz | 0.854 | -138.66 | 11.18 | 91.94 | 0.028 | 12.66 | 0.374 | -76.87 |
| 1.1 GHz | 0.849 | -143.98 | 10.31 | 87.79 | 0.028 | 9.64 | 0.368 | -80.34 |
| 1.2 GHz | 0.845 | -148.73 | 9.56 | 83.92 | 0.028 | 6.92 | 0.366 | -83.57 |
| 1.3 GHz | 0.842 | -153.01 | 8.90 | 80.29 | 0.028 | 4.46 | 0.365 | -86.61 |
| 1.4 GHz | 0.839 | -156.90 | 8.33 | 76.84 | 0.028 | 2.22 | 0.365 | -89.49 |
| 1.5 GHz | 0.837 | -160.49 | 7.82 | 73.56 | 0.028 | 0.15 | 0.367 | -92.24 |
| 1.6 GHz | 0.835 | -163.81 | 7.37 | 70.40 | 0.028 | -1.75 | 0.369 | -94.88 |
| 1.7 GHz | 0.833 | -166.92 | 6.96 | 67.36 | 0.028 | -3.51 | 0.373 | -97.43 |
| 1.8 GHz | 0.832 | -169.85 | 6.60 | 64.41 | 0.028 | -5.15 | 0.376 | -99.88 |
| 1.9 GHz | 0.830 | -172.62 | 6.27 | 61.54 | 0.028 | -6.67 | 0.381 | -102.27 |
| 2.0 GHz | 0.829 | -175.27 | 5.98 | 58.74 | 0.028 | -8.08 | 0.386 | -104.58 |
| 2.1 GHz | 0.828 | -177.81 | 5.71 | 56.00 | 0.028 | -9.40 | 0.391 | -106.84 |
| 2.2 GHz | 0.827 | 179.75 | 5.46 | 53.32 | 0.027 | -10.61 | 0.396 | -109.04 |
| 2.3 GHz | 0.826 | 177.38 | 5.24 | 50.68 | 0.027 | -11.73 | 0.401 | -111.19 |
| 2.4 GHz | 0.825 | 175.07 | 5.03 | 48.09 | 0.027 | -12.77 | 0.407 | -113.29 |
| 2.5 GHz | 0.824 | 172.82 | 4.84 | 45.53 | 0.027 | -13.71 | 0.412 | -115.36 |
| 2.6 GHz | 0.823 | 170.61 | 4.67 | 43.00 | 0.026 | -14.57 | 0.418 | -117.38 |
| 2.7 GHz | 0.821 | 168.44 | 4.51 | 40.50 | 0.026 | -15.34 | 0.423 | -119.36 |
| 2.8 GHz | 0.820 | 166.30 | 4.36 | 38.02 | 0.026 | -16.02 | 0.428 | -121.32 |
| 2.9 GHz | 0.819 | 164.18 | 4.22 | 35.57 | 0.026 | -16.62 | 0.434 | -123.24 |
| 3.0 GHz | 0.818 | 162.08 | 4.09 | 33.13 | 0.026 | -17.13 | 0.439 | -125.13 |
| 3.2 GHz | 0.816 | 157.91 | 3.85 | 28.31 | 0.025 | -17.89 | 0.449 | -128.84 |
| 3.4 GHz | 0.813 | 153.76 | 3.65 | 23.53 | 0.025 | -18.30 | 0.458 | -132.46 |
| 3.6 GHz | 0.810 | 149.58 | 3.47 | 18.78 | 0.025 | -18.38 | 0.467 | -136.00 |
| 3.8 GHz | 0.807 | 145.35 | 3.31 | 14.05 | 0.024 | -18.13 | 0.474 | -139.48 |
| 4.0 GHz | 0.804 | 141.05 | 3.18 | 9.32 | 0.024 | -17.60 | 0.481 | -142.91 |
| 4.2 GHz | 0.801 | 136.66 | 3.05 | 4.57 | 0.024 | -16.82 | 0.488 | -146.30 |
| 4.4 GHz | 0.797 | 132.15 | 2.94 | -0.20 | 0.025 | -15.89 | 0.493 | -149.67 |
| 4.6 GHz | 0.793 | 127.50 | 2.85 | -5.01 | 0.025 | -14.87 | 0.497 | -153.02 |
| 4.8 GHz | 0.789 | 122.70 | 2.76 | -9.86 | 0.026 | -13.89 | 0.500 | -156.37 |
| 5.0 GHz | 0.785 | 117.72 | 2.68 | -14.79 | 0.027 | -13.04 | 0.503 | -159.74 |
| 5.2 GHz | 0.780 | 112.55 | 2.62 | -19.78 | 0.029 | -12.42 | 0.504 | -163.14 |
| 5.4 GHz | 0.776 | 107.17 | 2.55 | -24.86 | 0.030 | -12.13 | 0.505 | -166.59 |
| 5.6 GHz | 0.772 | 101.58 | 2.50 | -30.03 | 0.032 | -12.22 | 0.504 | -170.10 |
| 5.8 GHz | 0.768 | 95.76 | 2.44 | -35.30 | 0.035 | -12.75 | 0.503 | -173.70 |
| 6.0 GHz | 0.764 | 89.70 | 2.40 | -40.69 | 0.037 | -13.73 | 0.501 | -177.41 |

 $To \ download \ the \ s\text{-parameters in s2p format, go to the CGH40006P} \ Product \ Page \ and \ click \ on \ the \ documentation \ tab.$



Product Dimensions CGH40006P (Package Type - 440109)





NOTES: (UNLESS OTHERWISE SPECIFIED)

- INTERPRET DRAWING IN ACCORDANCE WITH ANSI Y14.5M-1982 DIMENSIONING AND TOLERANCING.
- 2. CONTROLLING DIMENSION: INCH.
- 3. ALL PLATED SURFACES ARE Ni/Au

| | INC | HES | MILLIMETERS | | |
|-----|------|------|-------------|------|--|
| DIM | MIN | MAX | MIN | MAX | |
| Α | .135 | .145 | 3.43 | 3.68 | |
| В | .315 | .325 | 8.00 | 8.26 | |
| С | .155 | .165 | 3.94 | 4.19 | |
| D | .045 | .055 | 1.14 | 1.40 | |
| E | .195 | .205 | 4.95 | 5.21 | |
| F | .090 | .110 | 2.29 | 2.79 | |
| G | .007 | .009 | .178 | 0.23 | |
| Н | .026 | .030 | .660 | .762 | |
| I | .175 | .185 | 4.45 | 4.70 | |

PIN 1. GATE PIN 2. DRAIN PIN 3. SOURCE



Product Ordering Information

| Order Number | Description | Unit of Measure | Image |
|---------------|------------------------------------|-----------------|--------------|
| CGH40006P | GaN HEMT | Each | CREE COT 829 |
| CGH40006P-TB | Test board without GaN HEMT | Each | |
| CGH40006P-AMP | Test board with GaN HEMT installed | Each | |



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